MMVL3700T1

High Voltage Silicon Pin Diode

These devices are designed primarily for VHF band switching applications but are also suitable for use in general-purpose switching circuits. They are supplied in a cost-effective plastic surface mount package for economical, high-volume consumer and industrial requirements.

Features

- Long Reverse Recovery Time: $t_{rr} = 300 \text{ ns} (Typ)$
- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Series Resistance @ 100 MHz:
 - $R_S = 0.7 \ \Omega$ (Typ) @ $I_F = 10 \ mAdc$
- Reverse Breakdown Voltage = 200 V (Min)
- Pb–Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	200	Vdc
Peak Forward Current	١ _F	20	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation FR-5 Board, $T_A = 25^{\circ}C$ (Note 1) Derate above 25°C	P _D	200 1.57	mW mW/°C	
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	635	°C/W	
Junction and Storage Temperature	T _J , T _{stg}	150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

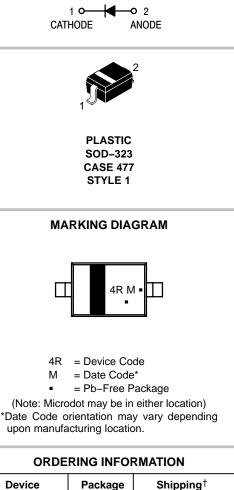
1. FR-4 Minimum Pad



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SILICON PIN SWITCHING DIODE



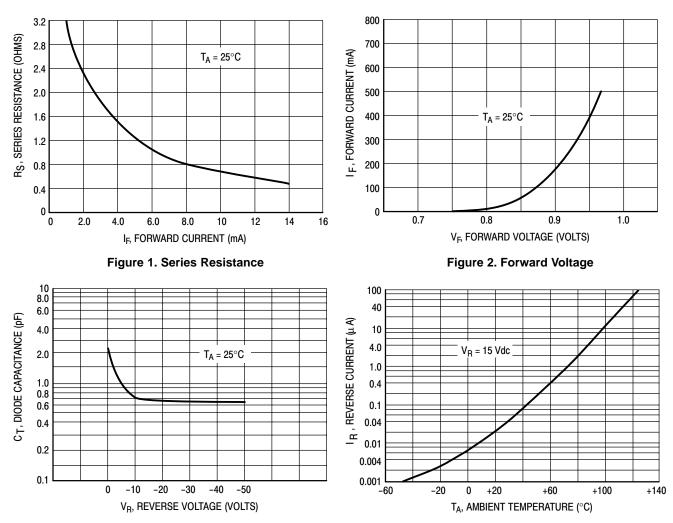
Device	Package	Shipping [†]
MMVL3700T1	SOD-323	3000/Tape & Reel
MMVL3700T1G	SOD-323 (Pb-Free)	3000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \ \mu Adc$)	V _{(BR)R}	200	-	-	Vdc
Diode Capacitance (V _R = 20 Vdc, f = 1.0 MHz)	C _T	-	-	1.0	pF
Series Resistance (I _F = 10 mAdc)	R _S	-	0.7	1.0	Ω
Reverse Leakage Current (V _R = 150 Vdc)	I _R	-	-	0.1	μAdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc})$	t _{rr}	-	300	-	ns



TYPICAL CHARACTERISTICS

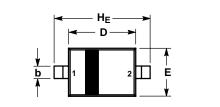
Figure 3. Diode Capacitance

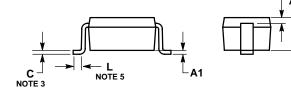
Figure 4. Leakage Current

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PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE G





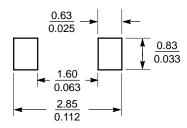
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
 LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
Е	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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